

## / MOS FIELD EFFECT TRANSISTOR NP40N055CLE, NP40N055DLE, NP40N055ELE

### SWITCHING N-CHANNEL POWER MOS FET INDUSTRIAL USE

### **DESCRIPTION**

These products are N-channel MOS Field Effect Transistor designed for high current switching applications.

### **FEATURES**

- Channel temperature 175 degree rated
- Super low on-state resistance
- $\bigstar$  RDS(on)1 = 23 m $\Omega$  MAX. (VGS = 10 V, ID = 20A)
- ★ RDS(on)2 =  $28 \text{ m}\Omega$  MAX. (VGS = 5.0 V, ID = 20 A)
- ★ Low Ciss: Ciss = 1300 pF TYP.
  - Built-in gate protection diode

### **ORDERING INFORMATION**

PART NUMBER	PACKAGE
NP40N055CLE	TO-220AB
NP40N055DLE	TO-262
NP40N055ELE	TO-263

### **ABSOLUTE MAXIMUM RATINGS (TA = 25°C)**

	Drain to Source Voltage	VDSS	55	V
	Gate to Source Voltage	Vgss	±20	V
	Drain Current (DC)	ID(DC)	±40	Α
	Drain Current (Pulse) Note1	D(pulse)	±160	Α
	Total Power Dissipation (T <sub>A</sub> = 25°C)	Рт	1.8	W
*	Total Power Dissipation (Tc = 25°C)	Рт	66	W
*	Single Avalanche Current Note2	las	29 / 21 / 8	Α
*	Single Avalanche Energy Note2	Eas	0.8 / 44 / 64	mJ
	Channel Temperature	$T_ch$	175	°C
	Storage Temperature	T <sub>stg</sub>	-55 to +175	°C

**Notes 1.** PW  $\leq$  10  $\mu$ s, Duty cycle  $\leq$  1 %

2. Starting T<sub>ch</sub> = 25°C, R<sub>G</sub> = 25  $\Omega$  , V<sub>GS</sub> = 20 V $\rightarrow$ 0 V

### THERMAL RESISTANCE

*	Channel to Case	Rth(ch-C)	2.27	°C/W
	Channel to Ambient	Rth(ch-A)	83.3	°C/W

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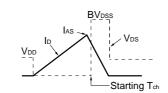


### **★** ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C)

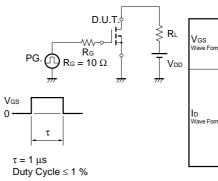
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Drain to Source On-state Resistance	RDS(on)1	Vgs = 10 V, ID = 20 A		18	23	mΩ
	RDS(on)2	Vgs = 5.0 V, Ip = 20 A		21	28	mΩ
	RDS(on)3	Vgs = 4.5 V, lb = 20 A		24	32	mΩ
Gate to Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	1.5	2.0	2.5	V
Forward Transfer Admittance	yfs	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 20 A	9	18		S
Drain Leakage Current	Ipss	V <sub>DS</sub> = 55 V, V <sub>GS</sub> = 0 V			10	μΑ
Gate to Source Leakage Current	lgss	Vgs = ±20 V, Vps = 0 V			±10	μΑ
Input Capacitance	Ciss	V <sub>DS</sub> = 25 V		1300	1950	pF
Output Capacitance	Coss	Vgs = 0 V		190	280	pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		92	170	pF
Turn-on Delay Time	td(on)	ID = 20 A		30	66	ns
Rise Time	tr	V <sub>GS(on)</sub> = 10 V		420	1050	ns
Turn-off Delay Time	td(off)	V <sub>DD</sub> = 28 V		73	150	ns
Fall Time	tf	$R_G = 10 \Omega$		120	300	ns
Total Gate Charge 1	Q <sub>G1</sub>	ID = 40 A, VDD = 44 V, VGS = 10 V		27	41	nC
Total Gate Charge 2	Q <sub>G2</sub>	ID = 40 A		15	23	nC
Gate to Source Charge	Qgs	VDD = 44 V		5		nC
Gate to Drain Charge	Q <sub>GD</sub>	Vgs = 5.0 V		8		nC
Body Diode Forward Voltage	V <sub>F</sub> (S-D)	IF = 40 A, VGS = 0 V		1.0		V
Reverse Recovery Time	trr	IF = 40 A, VGS = 0 V		40		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/μs		50		nC

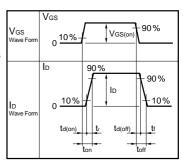
### **TEST CIRCUIT 1 AVALANCHE CAPABILITY**

# $\begin{array}{c} \text{D.U.T.} \\ \text{RG} = 25 \ \Omega \\ \text{VGS} = 20 \rightarrow 0 \ V \end{array} \begin{array}{c} \text{D.U.T.} \\ \text{S} \\ \text{50} \ \Omega \end{array}$



### **TEST CIRCUIT 2 SWITCHING TIME**



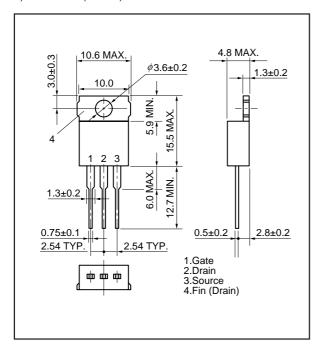


### **TEST CIRCUIT 3 GATE CHARGE**

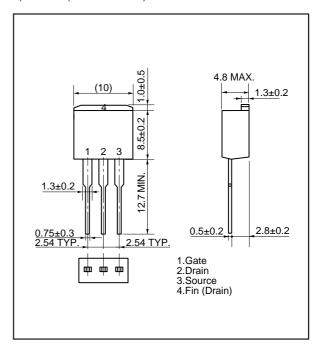
$$\begin{array}{c|c} D.U.T. \\ \hline \\ I_G = 2 \text{ mA} \\ \hline \\ \hline \\ PG. \\ \hline \\ \end{array} \begin{array}{c} S_{DL} \\ \hline \\ \\ \end{array} \begin{array}{c} R_L \\ \hline \\ \\ \end{array} \\ \begin{array}{c} V_{DD} \\ \hline \end{array}$$

### PACKAGE DRAWINGS (Unit: mm)

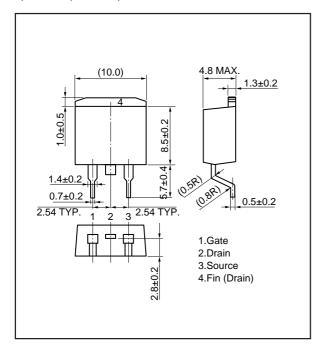
### 1) TO-220AB (MP-25)



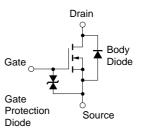
### 2) TO-262 (MP-25 Fin Cut)



### 3) TO-263 (MP-25ZJ)



### **EQUIVALENT CIRCUIT**



**Remark** The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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